



Title of Change:	Update to FPCN22548Z & FPCN22548ZA - Cancellation of previously announced Add Plasma Coating and 1x Reflow process for D2PAK devices assembled at Suzhou, China	
Proposed Changed Material First Ship Date:	5 August 2019	
Current Material Last Order Date:	N/A	
Current Material Last Delivery Date:	N/A	
Product Category:	Active components – Discrete components	
Contact information:	Contact your local ON Semiconductor Sales Office or <JiaNi.Wu@onsemi.com>	
Samples:	N/A	
Sample Availability Date:	N/A	
PPAP Availability Date:	N/A	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Jayoung.Hong @onsemi.com>.	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.	
Change Category	Type of Change	
Process – Assembly	Change of specified assembly process sequence (deletion and/or additional process step)	
Description and Purpose:		
This update is to notify customers the intended changes previously communicated in FPCN22548Z & FPCN22548ZA have been cancelled.		
FPCN22548Z & FPCN22548ZA included the following description:		
"This Final Notification announces to the customers the addition of Plasma Coating and Reflow process for D2PAK devices listed below."		
	Before Change Description	After Change Description
Assembly process	No Plasma Coating and reflow process	With Plasma Coating and reflow process
The intended change described above will not be implemented.		
Reason / Motivation for Change:	N/A	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.	
Sites Affected:	ON Semiconductor Sites: ON Suzhou, China	External Foundry/Subcon Sites: None



<p>Marking of Parts/ Traceability of Change:</p>	<p>N/A</p>
<p>Reliability Data Summary:</p> <p>N/A</p>	
<p>Electrical Characteristic Summary:</p> <p>Electrical characteristics are not impacted.</p>	
<p>List of Affected Parts:</p> <p>Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.</p> <p>FQB34P10TM-F085 FQB7P20TM-F085 FDB045AN08A0-F085 FQB7P20TM-F085P FQB34P10TM-F085P</p>	



Appendix A: Changed Products

Product	Customer Part Number	New Part Number	Qualification Vehicle
FDB045AN08A0-F085		NA	NA
FQB34P10TM-F085		NA	NA
FQB34P10TM-F085P		NA	NA
FQB7P20TM-F085		NA	NA